SDAS228A - JUNE 1982 - REVISED JANUARY 1995

- Compare Two 8-Bit Words
- Totem-Pole Outputs  $(\overline{P} = \overline{Q})$
- 'ALS688 Are Identical to 'ALS521
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

#### description

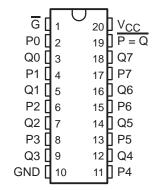
These identity comparators perform comparisons on two 8-bit binary or BCD words and provide  $\overline{P} = \overline{Q}$  outputs. These devices have totem-pole outputs.

The SN54ALS688 is characterized for operation over the full military temperature range of  $-55^{\circ}$ C to 125°C. The SN74ALS688 is characterized for operation from 0°C to 70°C.

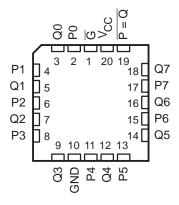
**FUNCTION TABLE** 

IN	PUTS	OUTDUT
DATA P, Q	ENABLE G	OUTPUT P = Q
P = Q	L	L
P > Q	L	Н
P < Q	L	Н
X	Н	Н

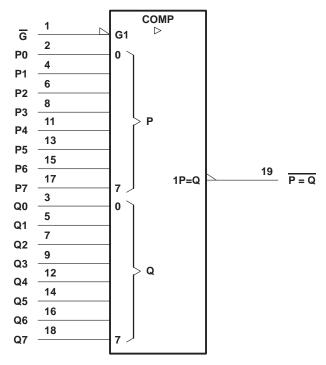
SN54ALS688 . . . J PACKAGE SN74ALS688 . . . DW OR N PACKAGE (TOP VIEW)



SN54ALS688 . . . FK PACKAGE (TOP VIEW)



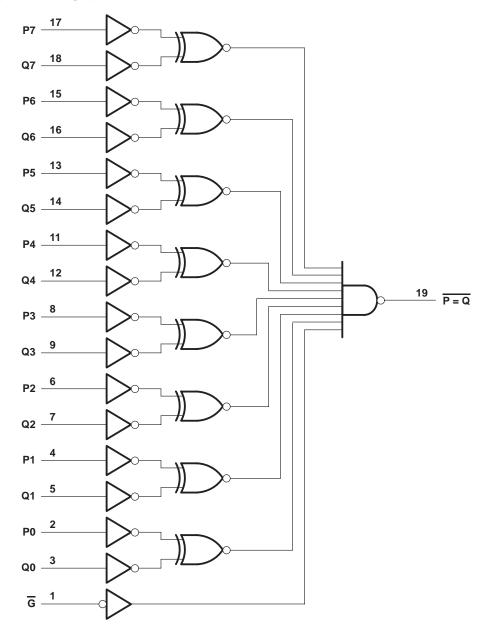
# logic symbol†



<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



#### logic diagram (positive logic)



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V <sub>CC</sub>	7 V
Input voltage, V <sub>I</sub>	7 V
Operating free-air temperature range, T <sub>A</sub> : SN54ALS688	−55°C to 125°C
SN74ALS688	0°C to 70°C
Storage temperature range	-65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



# SN54ALS688, SN74ALS688 **8-BIT IDENTITY COMPARATORS**

SDAS228A - JUNE 1982 - REVISED JANUARY 1995

#### recommended operating conditions

		SN	54ALS6	88	SN74ALS688			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V <sub>IL</sub>	Low-level input voltage			0.7			0.8	V
IOH	High-level output current			-1			-2.6	mA
loL	Low-level output current			12			24	mA
TA	Operating free-air temperature	-55		125	0		70	°C

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST OF	TEST CONDITIONS				SN	88	LINUT	
PARAMETER	IEST CC	MIN	TYP <sup>†</sup>	MAX	MIN	TYP <sup>†</sup>	MAX	UNIT	
VIK	V <sub>CC</sub> = 4.5 V,	$I_{I} = -18 \text{ mA}$			-1.5			-1.5	V
	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V <sub>CC</sub> -2	2		V <sub>CC</sub> -2	2		
Voн	V <sub>CC</sub> = 4.5 V	$I_{OH} = -1 \text{ mA}$	2.4	3.3					V
	VCC = 4.5 V	$I_{OH} = -2.6 \text{ mA}$				2.4	3.3		
VOL	V <sub>CC</sub> = 4.5 V	$I_{OL} = 12 \text{ mA}$		0.25	0.4		0.25	0.4	V
VOL.	VCC = 4.5 V	$I_{OL} = 24 \text{ mA}$					0.35	0.5	V
lį	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 7 V			0.1			0.1	mA
lН	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 2.7 V			20			20	μΑ
I <sub>IL</sub>	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 0.4 V			-0.1			-0.1	mA
I <sub>O</sub> ‡	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.25 V	-20		-112	-30		-112	mA
Icc	$V_{CC} = 5.5 \text{ V},$	See Note 1		12	19		12	19	mA

#### switching characteristics (see Figure 1)

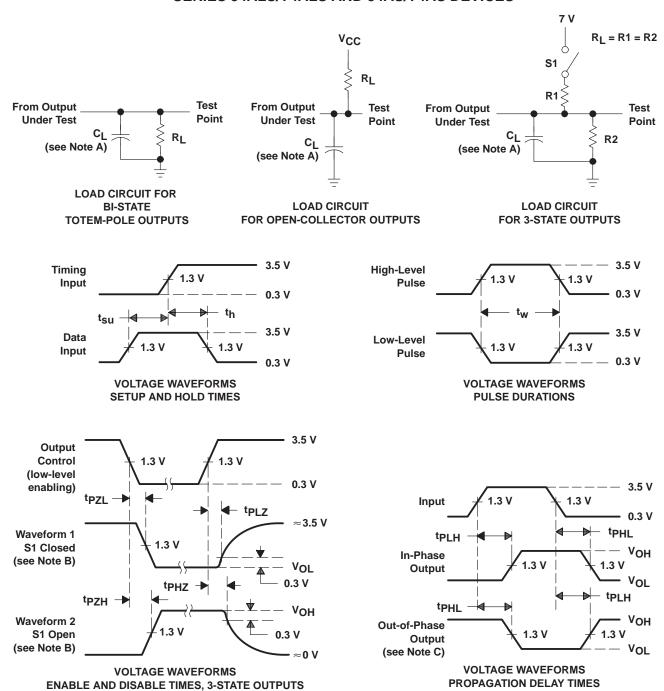
PARAMETER	FROM (INPUT)	TO (OUTPUT)	C <sub>L</sub>	= 50 pf = 500 g	V to 5.5 =, 2, to MAX§	V,	UNIT
			SN54A	LS688	SN74A		
			MIN	MAX	MIN	MAX	
<sup>t</sup> PLH	Р	$\overline{P} = Q$	3	16	3	12	ns
<sup>t</sup> PHL	P	P=Q	5	25	5	20	115
<sup>t</sup> PLH	0	$\overline{P} = Q$	3	16	3	12	20
<sup>t</sup> PHL	Q	P = Q	5	25	5	20	ns
t <sub>PLH</sub>	G	$\overline{P} = Q$	3	15	3	12	ns
t <sub>PHL</sub>	G	Γ≡Q	5	25	5	22	115

<sup>§</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



<sup>†</sup> All typical values are at  $V_{CC} = 5$  V,  $T_A = 25^{\circ}$ C. ‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current,  $I_{CC}$ . NOTE 1:  $I_{CC}$  is measured with  $\overline{G}$  grounded, P and Q at 4.5 V.

# PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR  $\leq$  1 MHz,  $t_{\Gamma}$  =  $t_{f}$  = 2 ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



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#### **PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-88578012A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 88578012A SNJ54ALS 688FK	Samples
5962-8857801RA	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8857801RA SNJ54ALS688J	Samples
5962-8857801SA	ACTIVE	CFP	W	20	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8857801SA SNJ54ALS688W	Samples
SN54ALS688J	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54ALS688J	Samples
SN74ALS688DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS688	Samples
SN74ALS688N	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS688N	Samples
SN74ALS688NSR	ACTIVE	SO	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS688	Samples
SNJ54ALS688FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 88578012A SNJ54ALS 688FK	Samples
SNJ54ALS688J	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8857801RA SNJ54ALS688J	Samples
SNJ54ALS688W	ACTIVE	CFP	W	20	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8857801SA SNJ54ALS688W	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

PACKAGE OPTION ADDENDUM

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**Green:** TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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#### OTHER QUALIFIED VERSIONS OF SN54ALS688, SN74ALS688:

Catalog: SN74ALS688

Military: SN54ALS688

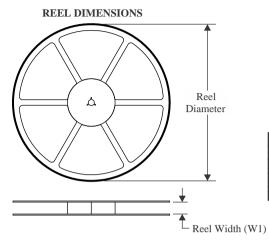
NOTE: Qualified Version Definitions:

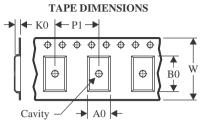
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

# **PACKAGE MATERIALS INFORMATION**

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#### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS688DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74ALS688NSR	so	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1

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#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS688DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ALS688NSR	SO	NS	20	2000	367.0	367.0	45.0

# **PACKAGE MATERIALS INFORMATION**

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#### **TUBE**



\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-88578012A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-8857801SA	W	CFP	20	25	506.98	26.16	6220	NA
SN74ALS688N	N	PDIP	20	20	506	13.97	11230	4.32
SNJ54ALS688FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54ALS688W	W	CFP	20	25	506.98	26.16	6220	NA

#### **MECHANICAL DATA**

# NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



### 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



# N (R-PDIP-T\*\*)

# PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOIC



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



# W (R-GDFP-F20)

# CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.

  D. Index point is provided on cap for terminal identification only.

  E. Falls within Mil—Std 1835 GDFP2—F20



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